

MOS FIELD EFFECT TRANSISTOR

μ PA2723UT1A

SWITCHING

N-CHANNEL POWER MOSFET

DESCRIPTION

The μ PA2723UT1A is N-channel MOSFET designed for low side device of synchronous rectifier DC/DC converter.

FEATURES

- Low on-state resistance
 $R_{DS(on)1} = 2.5 \text{ m}\Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 17 \text{ A)}$
 $R_{DS(on)2} = 3.5 \text{ m}\Omega \text{ MAX. (} V_{GS} = 4.5 \text{ V, } I_D = 17 \text{ A)}$
- Thin type surface mount package with heat spreader (8-pin HVSON)
- RoHS Compliant

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, All terminals are connected.)

Drain to Source Voltage (V _{GS} = 0 V)	V _{DSS}	30	V
Gate to Source Voltage (V _{DS} = 0 V)	V _{GSS}	±20	V
Drain Current (DC)	I _{D(DC)}	±33	A
Drain Current (pulse) ^{Note1}	I _{D(pulse)}	±200	A
Total Power Dissipation ^{Note2}	P _{T1}	1.5	W
Total Power Dissipation (PW = 10 sec) ^{Note2}	P _{T2}	4.6	W
Channel Temperature	T _{ch}	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C
Single Avalanche Current ^{Note3}	I _{AS}	33	A
Single Avalanche Energy ^{Note3}	E _{AS}	109	mJ

THERMAL RESISTANCE

Channel to Ambient Thermal Resistance ^{Note2}	R _{th(ch-A)}	83.3	°C/W
Channel to Case (Drain) Thermal Resistance	R _{th(ch-C)}	1.5	°C/W

Notes 1. PW ≤ 10 μs, Duty Cycle ≤ 1%

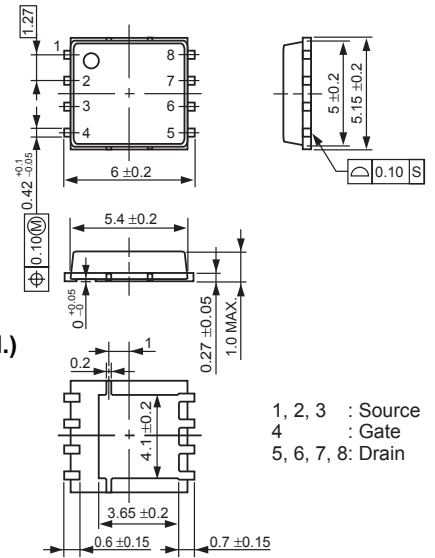
2. Mounted on a glass epoxy board of 25.4 mm x 25.4 mm x 0.8 mm

3. Starting T_{ch} = 25°C, V_{DD} = 15 V, R_G = 25 Ω, V_{GS} = 20 → 0 V, L = 100 μH

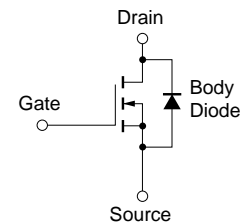
Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT

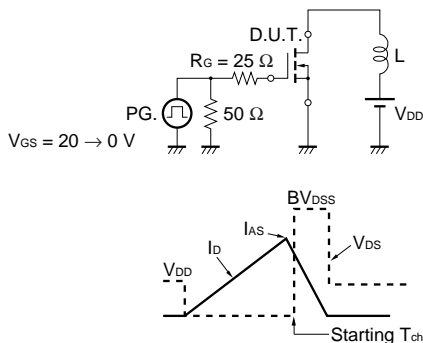


ELECTRICAL CHARACTERISTICS (TA = 25°C, All terminals are connected.)

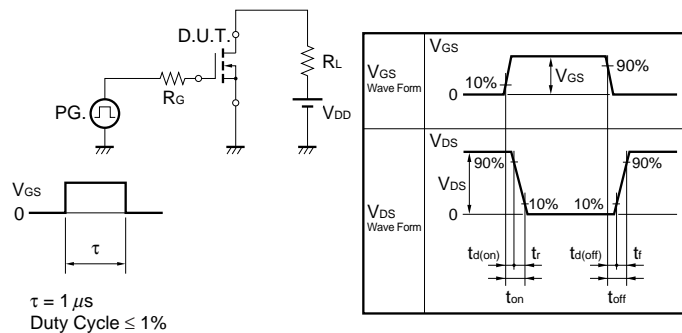
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			10	μA
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$			±100	nA
Gate to Source Cut-off Voltage	$V_{GS(off)}$	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	1.0		2.5	V
Forward Transfer Admittance ^{Note}	$ y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 17\text{ A}$	17			S
Drain to Source On-state Resistance ^{Note}	$R_{DS(on)1}$	$V_{GS} = 10\text{ V}, I_D = 17\text{ A}$		1.9	2.5	mΩ
	$R_{DS(on)2}$	$V_{GS} = 4.5\text{ V}, I_D = 17\text{ A}$		2.6	3.5	mΩ
Input Capacitance	C_{iss}	$V_{DS} = 10\text{ V},$		8100		pF
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V},$		1290		pF
Reverse Transfer Capacitance	C_{rss}	$f = 1\text{ MHz}$		610		pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}, I_D = 17\text{ A},$		30		ns
Rise Time	t_r	$V_{GS} = 10\text{ V},$		40		ns
Turn-off Delay Time	$t_{d(off)}$	$R_G = 10\ \Omega$		160		ns
Fall Time	t_f			55		ns
Total Gate Charge	Q_G	$V_{DD} = 15\text{ V},$		64		nC
Gate to Source Charge	Q_{GS}	$V_{GS} = 5\text{ V},$		19		nC
Gate to Drain Charge	Q_{GD}	$I_D = 33\text{ A}$		24		nC
Body Diode Forward Voltage ^{Note}	$V_{F(S-D)}$	$I_F = 33\text{ A}, V_{GS} = 0\text{ V}$		0.76		V
Reverse Recovery Time	t_{rr}	$I_F = 33\text{ A}, V_{GS} = 0\text{ V},$		55		ns
Reverse Recovery Charge	Q_{rr}	$di/dt = 100\text{ A}/\mu\text{s}$		66		nC
Gate Resistance	R_G	$f = 1\text{ MHz}$		1.4		Ω

Note Pulsed

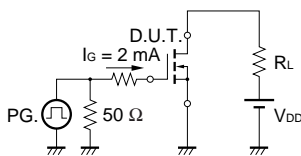
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 2 SWITCHING TIME

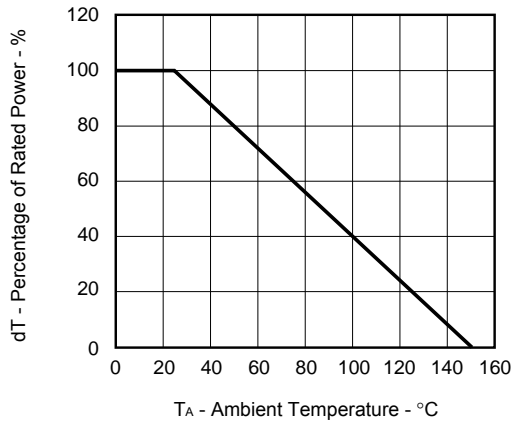


TEST CIRCUIT 3 GATE CHARGE

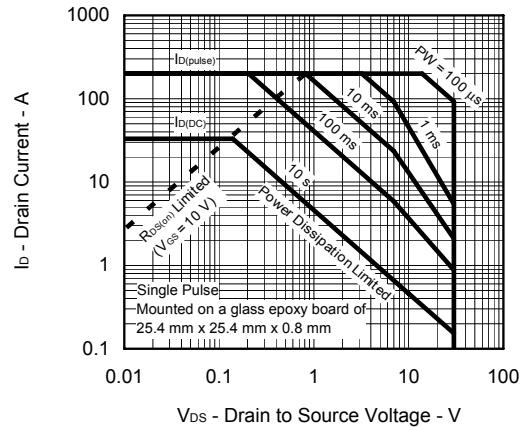


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

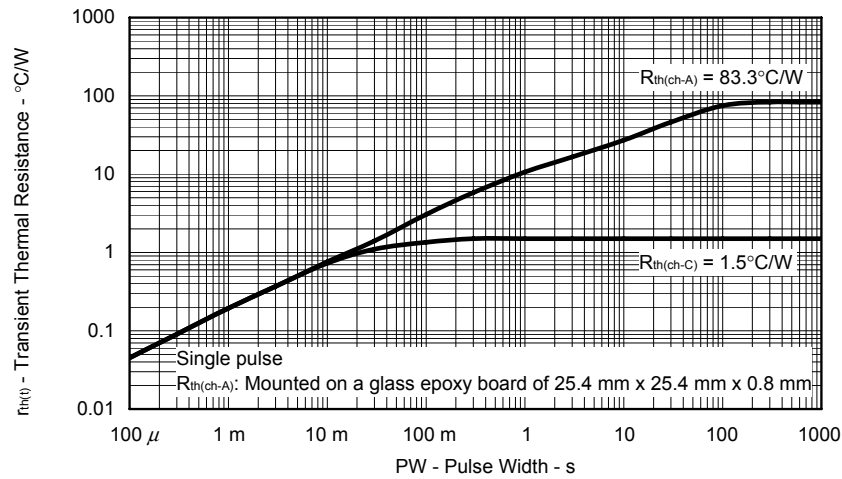
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



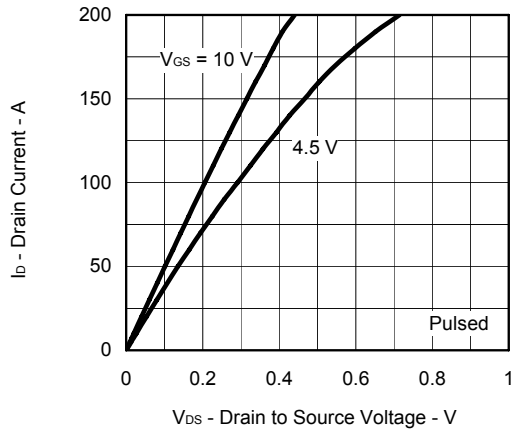
FORWARD BIAS SAFE OPERATING AREA



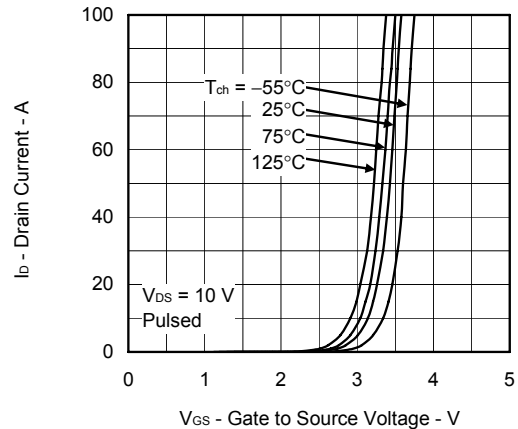
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

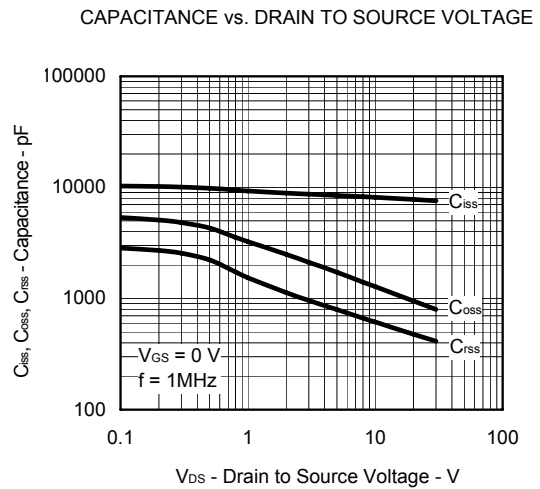
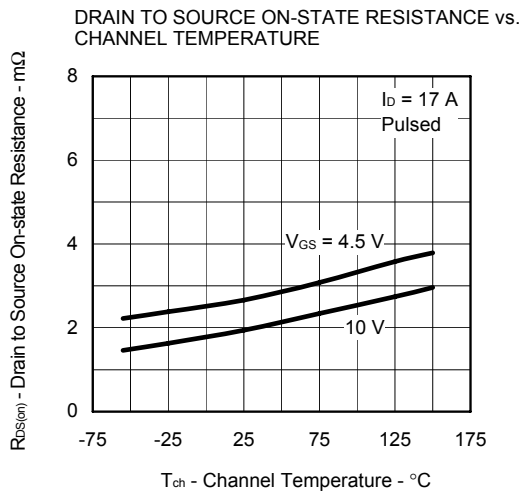
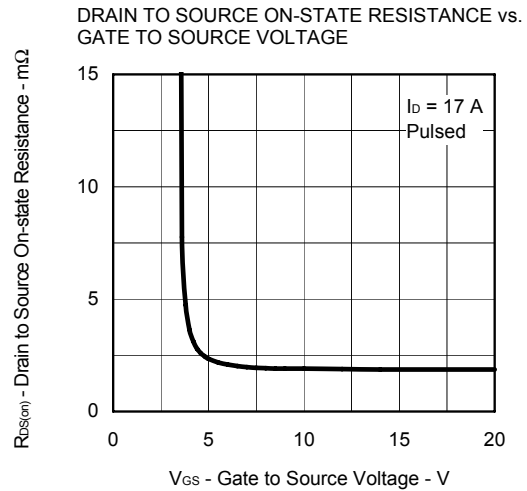
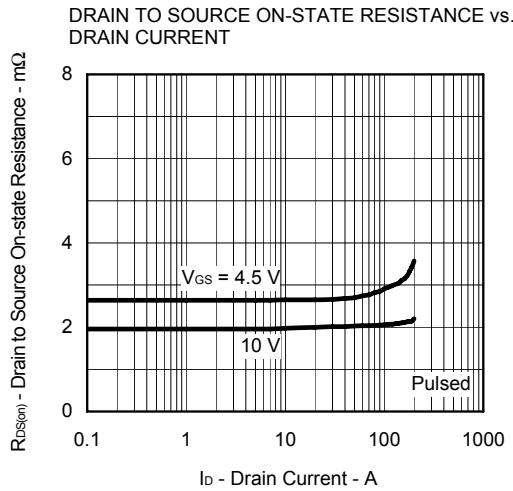
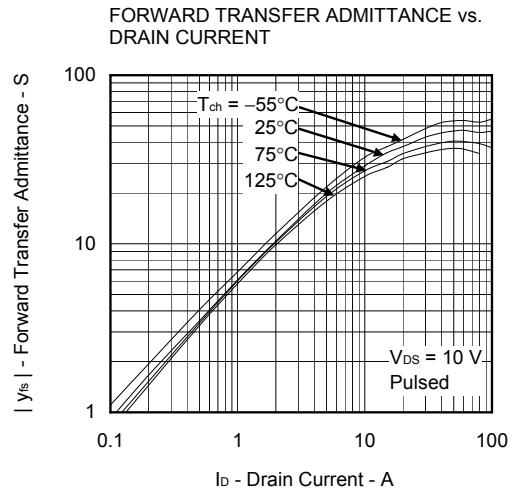
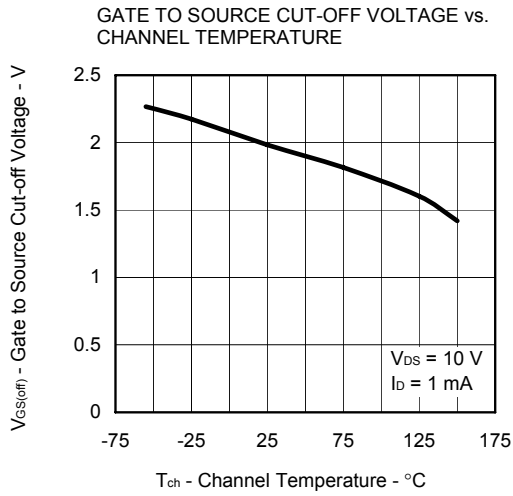


DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

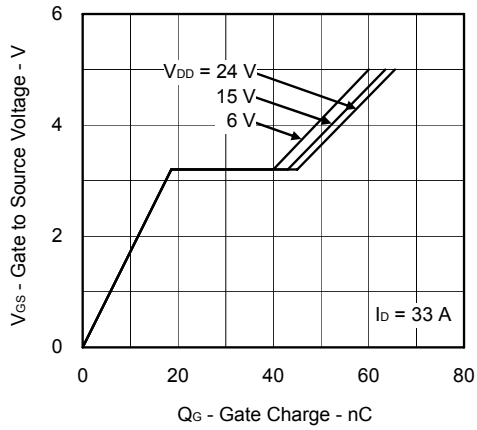


FORWARD TRANSFER CHARACTERISTICS

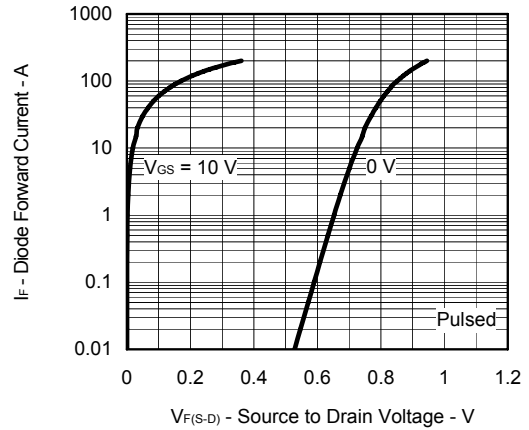




DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
μPA2723UT1A-E1-AZ ^{Note}	Sn-Bi	Tape 3000 p/reel	8-pin HVSON 0.10 g TYP.
μPA2723UT1A-E2-AZ ^{Note}			
μPA2723UT1A-E1-AY ^{Note}	Pure Sn		
μPA2723UT1A-E2-AY ^{Note}			

Note Pb-free (This product does not contain Pb in the external electrode.)

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